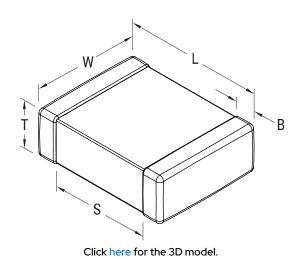


C1812C331KHGACTU

Aliases (C1812C331KHGAC7800) SMD Comm COG HV, Ceramic, 330 pF, 10%, 3,000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1812, 2.3 mm



General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	87 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	2.5mm +/-0.20mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

W	3.2mm +/-0.3mm
Т	2.5mm +/-0.20mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

Specifications		
Capacitance	330 pF	
Measurement Condition	1 MHz 1.0Vrms	
Tolerance	10%	
Voltage DC	3000 VDC	
Dielectric Withstanding Voltage	3,600 VDC	
Temperature Range	-55/+125°C	
Temp. Coefficient	COG	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
Dissipation Factor	0.1% 1 MHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour	
Insulation Resistance	100 GOhms	

		Capacitance
Packaging	T&R, 180mm, Plastic Tape	Reference to Applied (TCC
Packaging Quantity	500	Dissipation Fa

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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